SiHH21N60EF



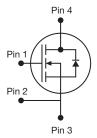
Vishay Siliconix

E Series Power MOSFET with Fast Body Diode

PRODUCT SUMMARY					
V _{DS} (V) at T _J max.	650				
R _{DS(on)} typ. (Ω) at 25 °C	V _{GS} = 10 V 0.161				
Q _g max. (nC)	86				
Q _{gs} (nC)	13				
Q _{gd} (nC)	23				
Configuration	Single				

PowerPAK[®] 8 x 8





N-Channel MOSFET

FEATURES

- Completely lead (Pb)-free device
- Low figure-of-merit (FOM) Ron x Qg
- Low input capacitance (Ciss)
- Reduced switching and conduction losses
- Ultra low gate charge (Q_g)
- Avalanche energy rated (UIS)
- · Kelvin connection for reduced gate noise
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Renewable energy
 - Solar (PV inverters)

ORDERING INFORMATION	
Package	PowerPAK 8 x 8
Lead (Pb)-free and Halogen-free	SiHH21N60EF-T1-GE3

ABSOLUTE MAXIMUM RATINGS	$(T_C = 25 \ ^\circ C, un$	less otherwis	se noted)		
PARAMETER			SYMBOL	LIMIT	UNIT
Drain-Source Voltage			V _{DS}	600	v
Gate-Source Voltage			V _{GS}	± 30	v
Continuous Drain Current (T _J = 150 °C)	V _{GS} at 10 V	T _C = 25 °C	- I _D	19	
	VGS AL TO V	T _C = 100 °C		12	А
Pulsed Drain Current ^a			I _{DM}	47	
Linear Derating Factor				1.4	W/°C
Single Pulse Avalanche Energy ^b			E _{AS}	226	mJ
Maximum Power Dissipation			PD	174	W
Operating Junction and Storage Temperature Range			T _J , T _{stg}	-55 to +150	°C
Drain-Source Voltage Slope	T _J =	T _J = 125 °C		70	1//22
Reverse Diode dV/dt c			dV/dt	20	V/ns

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature.

b. V_{DD} = 50 V, starting T_J = 25 °C, L = 28.2 mH, R_g = 25 Ω , I_{AS} = 4 A.

c. $I_{SD} \leq I_D,\, dI/dt$ = 100 A/µs, starting T_J = 25 °C.

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COMPLIANT

HALOGEN

FREE



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THERMAL RESISTANCE RATI	NGS							
PARAMETER	SYMBOL	TYP.		MAX.		UNIT		
Maximum Junction-to-Ambient	R _{thJA}	40	52			0044		
Maximum Junction-to-Case (Drain)	R _{thJC}	0.55 0.72				°C/W		
			-					
SPECIFICATIONS ($T_J = 25 \degree C$, u	Inless otherwi	se noted)						
PARAMETER	SYMBOL	1	T CONDITI	ONS	MIN.	TYP.	MAX.	UNIT
Static								
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} =	= 0 V, I _D = 2	50 µA	600	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	e to 25 °C, I	_D = 10 mA	-	0.63	-	V/°C
Gate-Source Threshold Voltage (N)	V _{GS(th)}	V _{DS} =	V_{GS} , $I_D = 2$	50 µA	2.0	-	4.0	V
Cata Sauraa Laakaga		, v	$V_{\rm GS} = \pm 20$ V	V	-	-	± 100	nA
Gate-Source Leakage	I _{GSS}	, v	/ _{GS} = ± 30 \	V	-	-	± 1	μA
Zaro Cata Valtaga Drain Current		V _{DS} =	480 V, V _{GS}	= 0 V	-	-	1	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 480 V	, V _{GS} = 0 V,	T _J = 125 °C	-	-	100	μA
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D	= 11 A	-	0.161	0.185	Ω
Forward Transconductance	9 _{fs}	V _{DS} = 30 V, I _D = 11 A		-	7.3	-	S	
Dynamic								
Input Capacitance	C _{iss}		$V_{GS} = 0 V,$		-	2035	-	_
Output Capacitance	C _{oss}	,	V _{DS} = 100 V	,	-	96	-	
Reverse Transfer Capacitance	C _{rss}	f = 1 MHz		-	6	-	pF	
Effective Output Capacitance, Energy Related ^a	C _{o(er)}	V_{DS} = 0 V to 480 V, V_{GS} = 0 V		-	60	-		
Effective Output Capacitance, Time Related ^b	C _{o(tr)}			-	257	-		
Total Gate Charge	Qg		V _{GS} = 10 V I _D = 11 A, V _{DS} = 480 V		-	57	86	nC
Gate-Source Charge	Q_gs	$V_{GS} = 10 V$			-	13	-	
Gate-Drain Charge	Q _{gd}				-	23	-	1
Turn-On Delay Time	t _{d(on)}			-	20	40		
Rise Time	t _r	V _{DD} =	480 V, I _D =	11 A,	-	43	86	ns
Turn-Off Delay Time	t _{d(off)}	V _{GS} =	$V_{GS} = 10 \text{ V}, \text{ R}_{g} = 9.1 \Omega$		-	65	98	115
Fall Time	t _f			-	43	86		
Gate Input Resistance	R _g	f = 1 MHz, open drain		0.25	0.8	1.0	Ω	
Drain-Source Body Diode Characteristic	cs							
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	19	A	
Pulsed Diode Forward Current	I _{SM}			-	-	47		
Diode Forward Voltage	V _{SD}	T _J = 25 °C, I _S = 11 A, V _{GS} = 0 V		-	0.9	1.2	V	
Reverse Recovery Time	t _{rr}	_			-	137	274	ns
Reverse Recovery Charge	Q _{rr}	$T_J = 25 \ ^{\circ}C, I_F = I_S = 11 \ A,$ dI/dt = 100 A/µs, V _R = 25 V		-	0.8	1.6	μC	
Reverse Recovery Current	I _{RRM}			-	12	-	А	

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS} .

b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS} .



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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

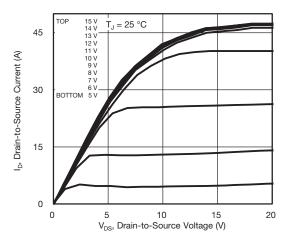


Fig. 1 - Typical Output Characteristics

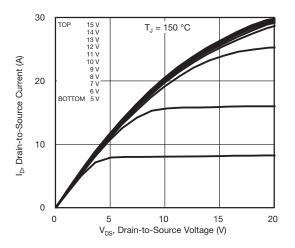
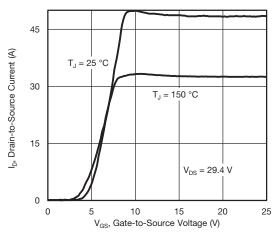


Fig. 2 - Typical Output Characteristics





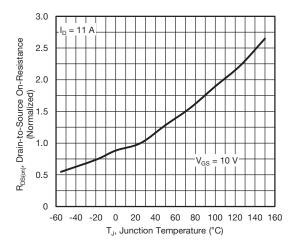


Fig. 4 - Normalized On-Resistance vs. Temperature

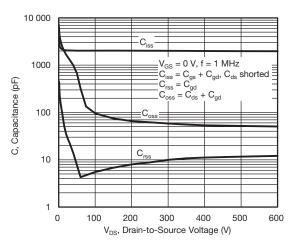


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

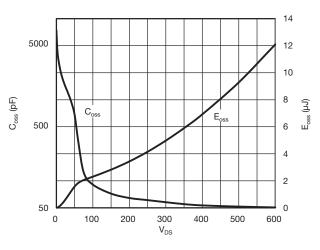


Fig. 6 - C_{OSS} and E_{OSS} vs. V_{DS}

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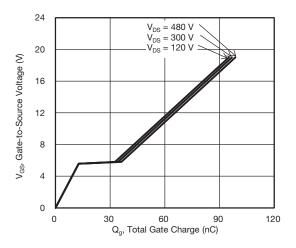


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

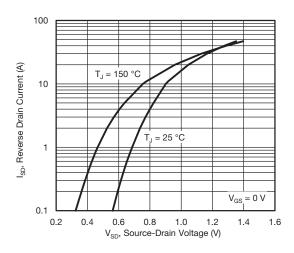


Fig. 8 - Typical Source-Drain Diode Forward Voltage

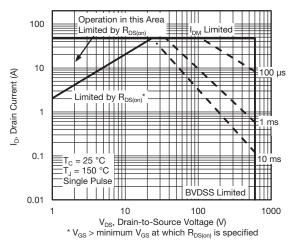


Fig. 9 - Maximum Safe Operating Area

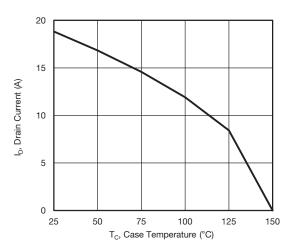


Fig. 10 - Maximum Drain Current vs. Case Temperature

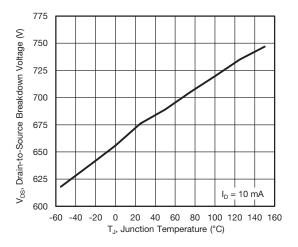


Fig. 11 - Temperature vs. Drain-to-Source Voltage

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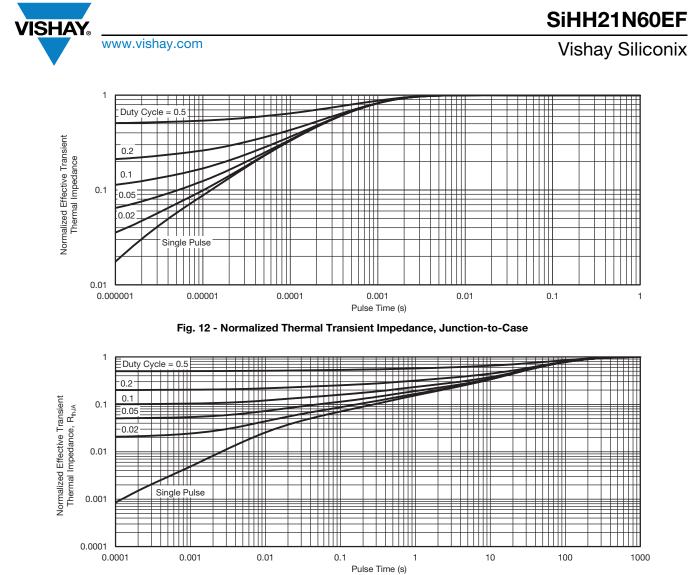


Fig. 13 - Normalized Thermal Transient Impedance, Junction-to-Ambient

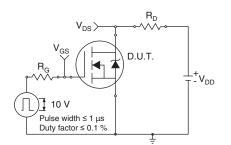


Fig. 14 - Switching Time Test Circuit

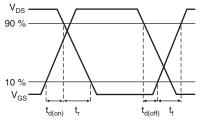


Fig. 15 - Switching Time Waveforms

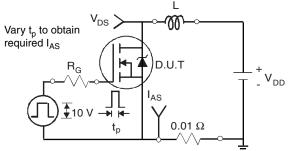


Fig. 16 - Unclamped Inductive Test Circuit

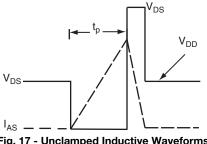
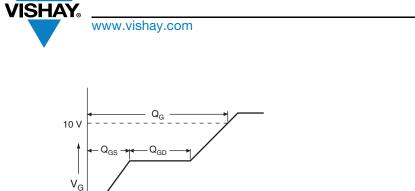


Fig. 17 - Unclamped Inductive Waveforms

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Charge -----

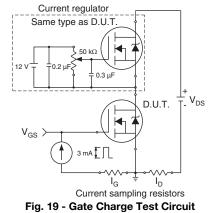


Fig. 18 - Basic Gate Charge Waveform



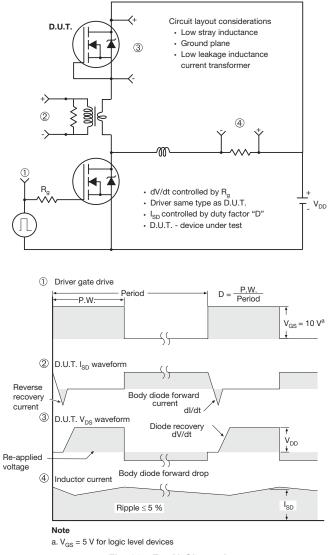


Fig. 20 - For N-Channel

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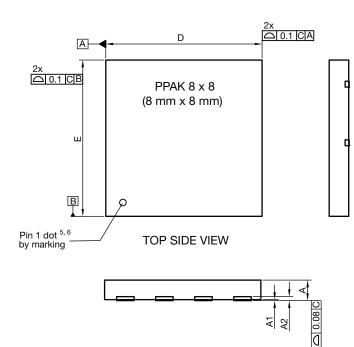
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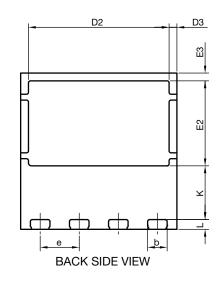
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PowerPAK[®] 8 x 8 Case Outline





DIM	MILLIMETERS			INCHES			
DIM.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	
А	0.95	1.00	1.05	0.037	0.039	0.041	
A1	0.00	-	0.05	0.000	-	0.002	
A2		020 ref.			0.008 ref.		
b	0.95	1.00	1.05	0.037	0.039	0.041	
D	7.90	8.00	8.10	0.311	0.315	0.319	
D2	7.10	7.20	7.30	0.280	0.283	0.287	
D3	0.40 BSC			0.016 BSC			
е	2.00 BSC		0.079 BSC				
E	7.90	8.00	8.10	0.311	0.315	0.319	
E2	4.30	4.35	4.40	0.169	0.171	0.173	
E3	0.40 BSC				0.016 BSC		
К	2.75 BSC		0.108 BSC				
L	0.45	0.50	0.55	0.018	0.020	0.022	
N ⁽³⁾	8				8		

Notes

⁽¹⁾ Use millimeters as the primary measurement

⁽²⁾ Dimensioning and tolerances conform to ASME Y14.5 M - 1994

⁽³⁾ N is the number of terminals

⁽⁴⁾ The pin 1 identifier must be existed on the top surface of the package by using indentation mark or other feature of package body

⁽⁵⁾ Exact shape and size of this feature is optional

ECN: E20-0518-Rev. B, 28-Sep-2020 DWG: 6041

Revision: 28-Sep-2020

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Recommended Minimum PADs for PowerPAK[®] 8 mm x 8 mm



Dimensions in millimeters

Document Number: 68441



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